



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD025N06N		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000965714							
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		342.08 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	18.334	5.36	5.36	53594	53594	
leadframe	non noble metal	iron	7439-89-6	0.166	0.05		487		
	inorganic material	phosphorus	7723-14-0	0.050	0.01		146		
	non noble metal	copper	7440-50-8	166.274	48.61	48.67	486062	486695	
wire	non noble metal	aluminium	7429-90-5	4.562	1.33	1.33	13335	13335	
encapsulation	organic material	carbon black	1333-86-4	1.201	0.35		3511		
	plastics	epoxy resin	-	21.021	6.15		61451		
	inorganic material	silicondioxide	60676-86-0	97.900	28.62	35.12	286186	351148	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.09	1.09	10933	10933	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		10		
	non noble metal	nickel	7440-02-0	1.421	0.42	0.42	4153	4163	
solder	non noble metal	tin	7440-31-5	0.548	0.16		1603		
	noble metal	silver	7440-22-4	0.685	0.20		2003		
	non noble metal	lead	7439-92-1	26.178	7.65	8.01	76526	80132	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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